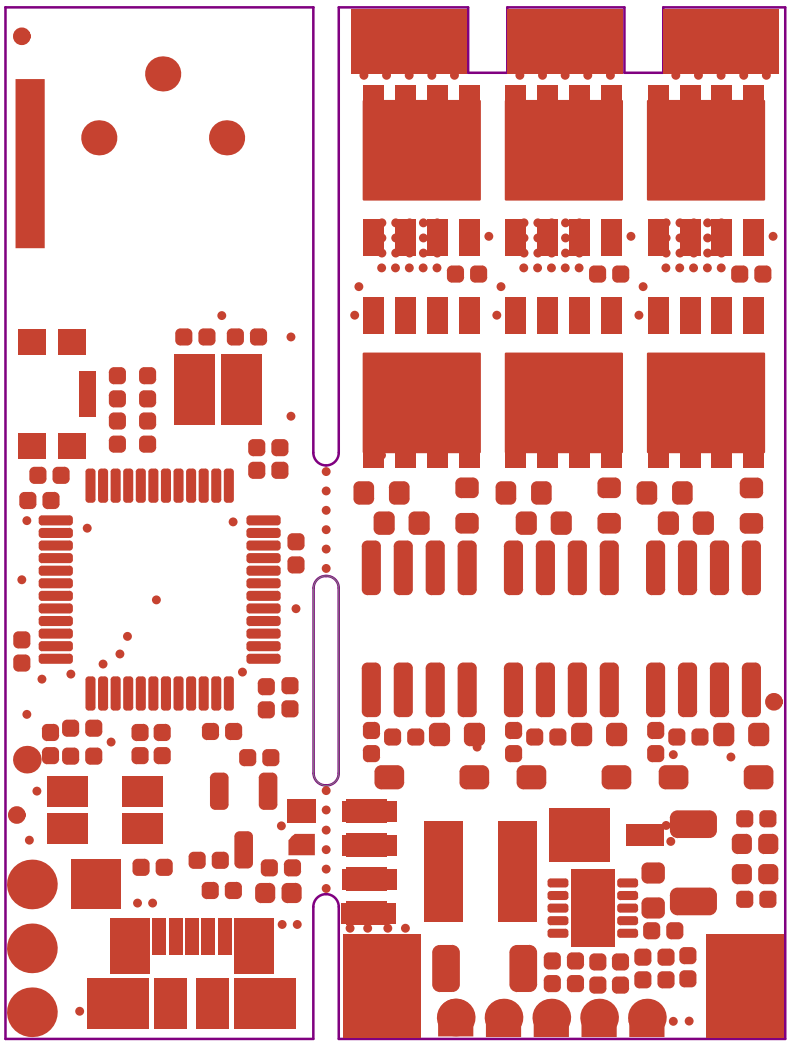


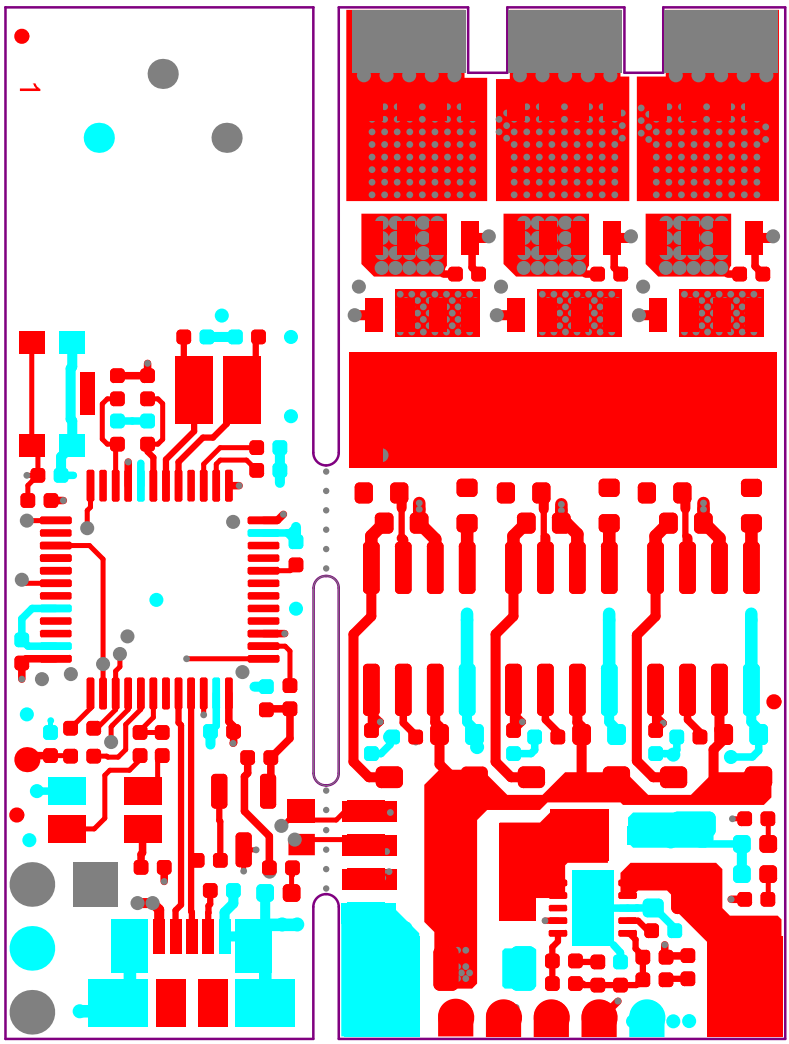
Top Overlay

.GTO



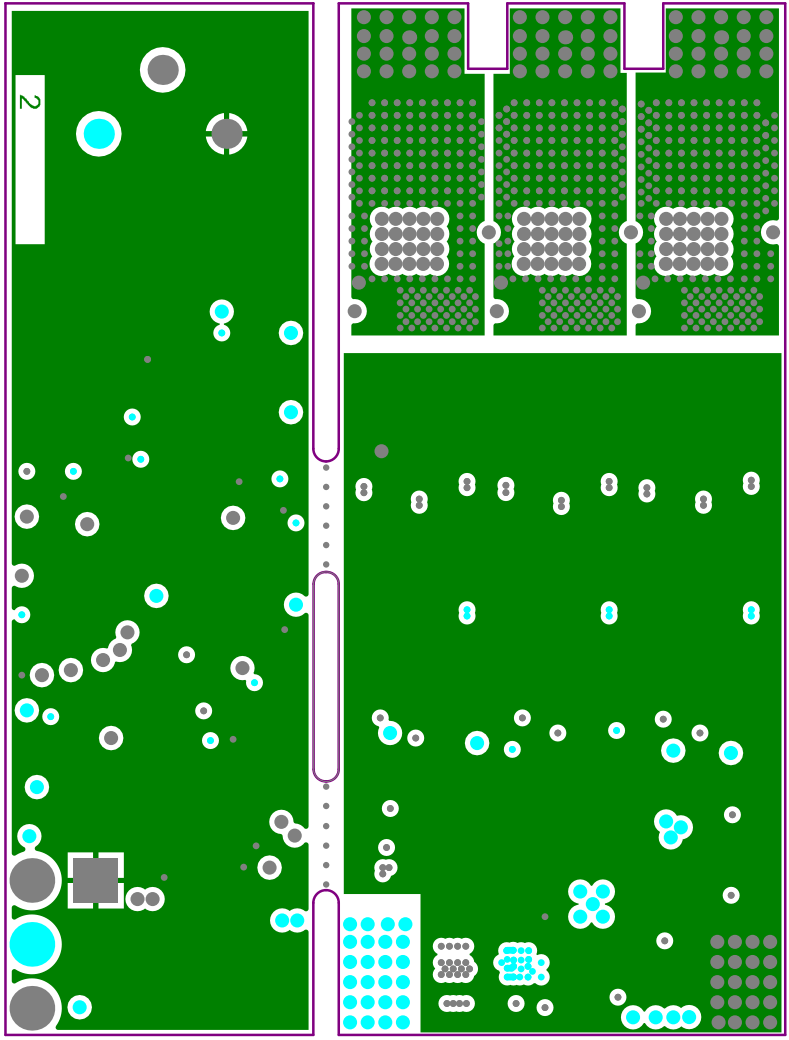
Top Solder

.GTS



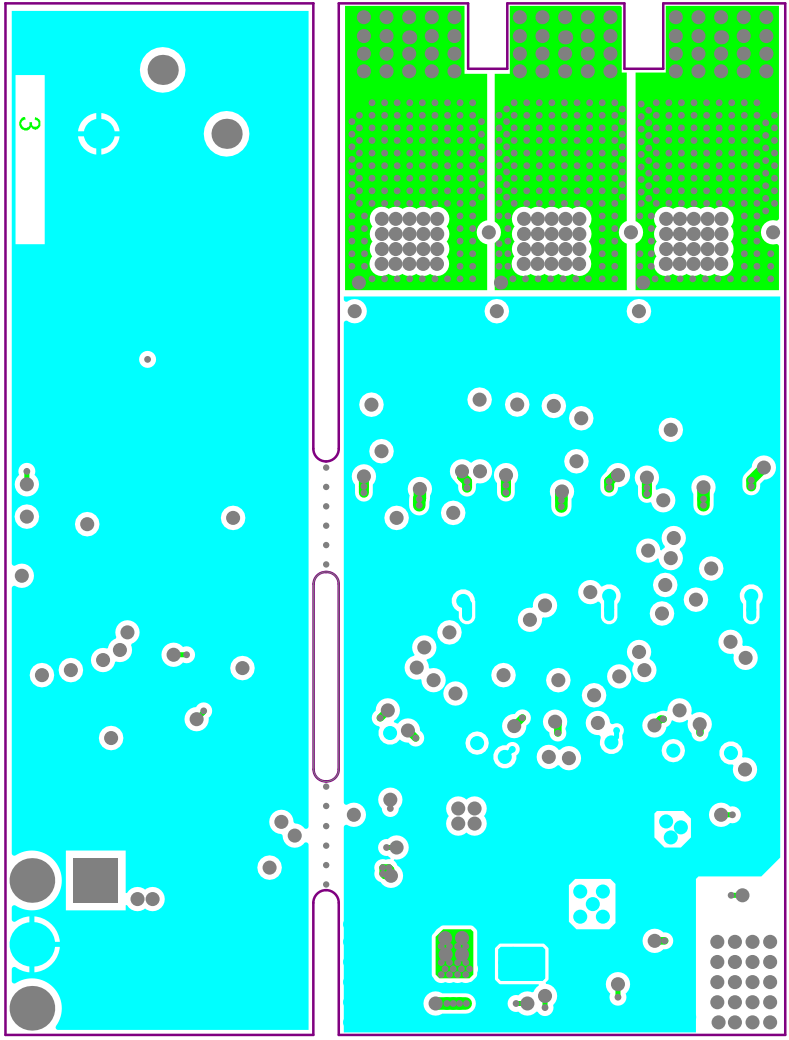
Top Layer

.GTL



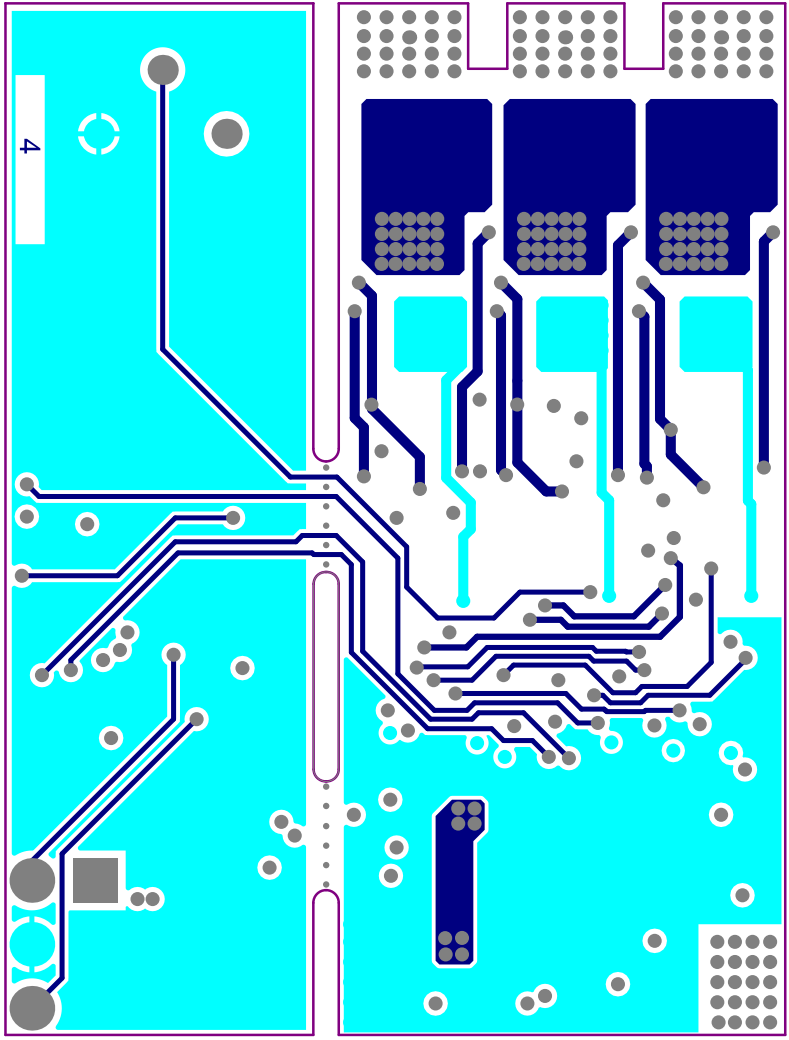
Signal Layer 1

.G1



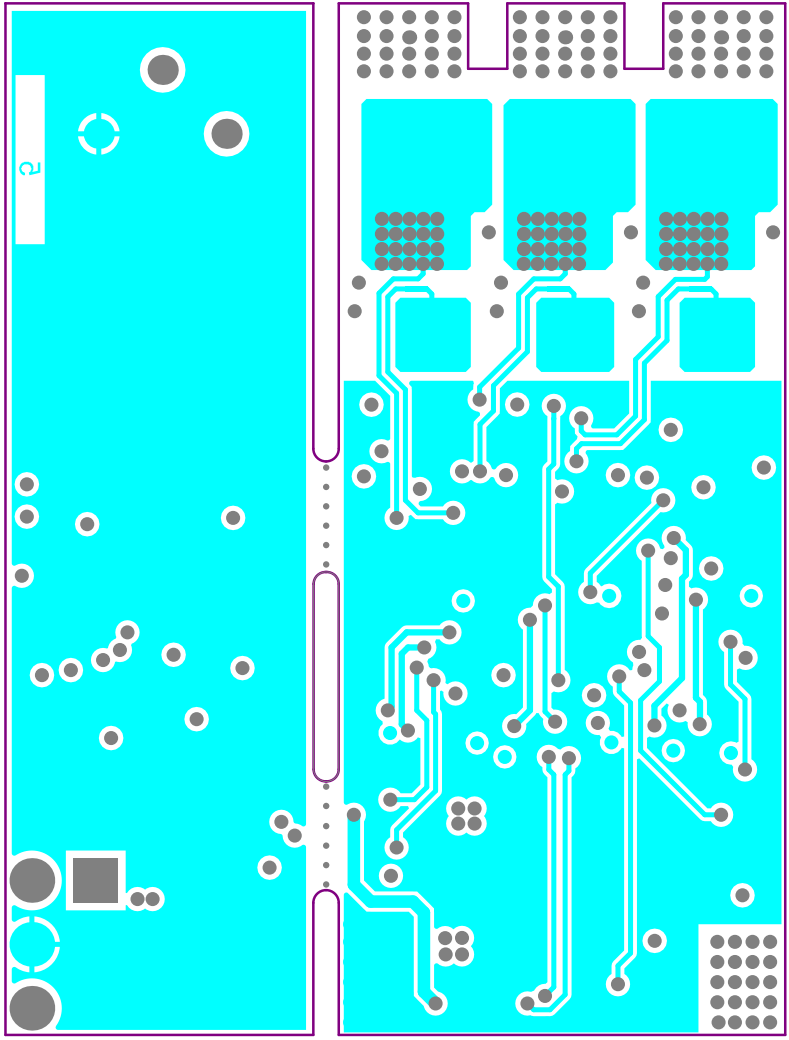
Signal Layer 2

.G2



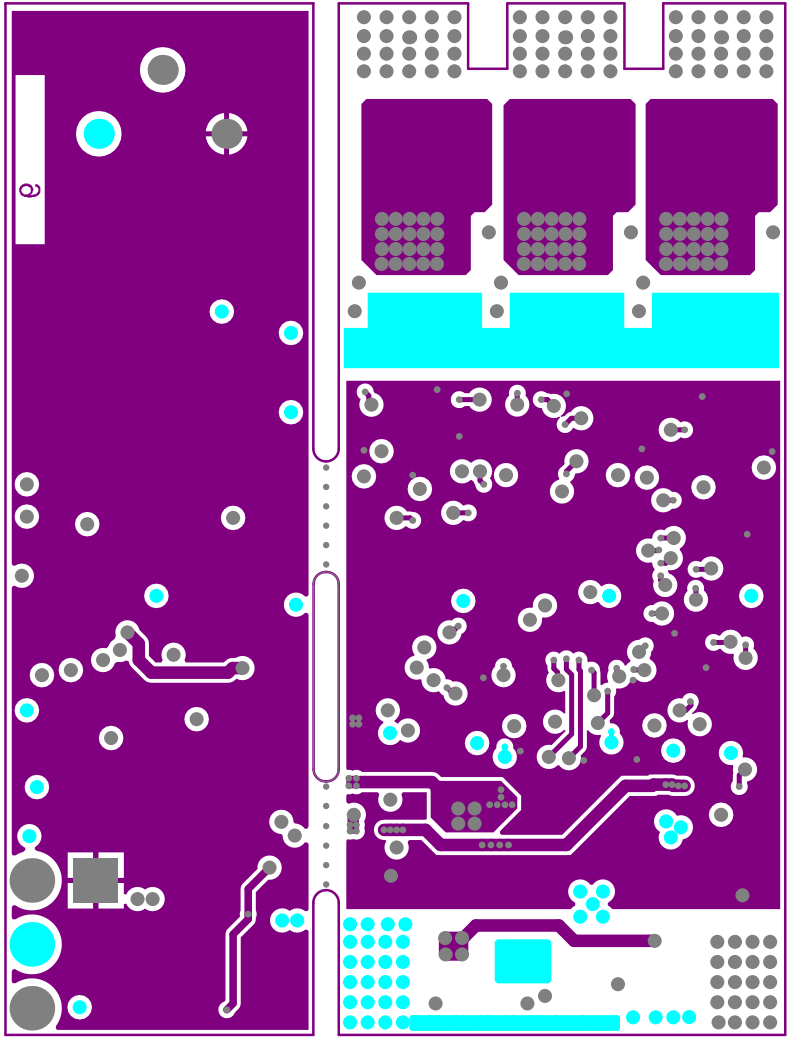
Signal Layer 3

.G3



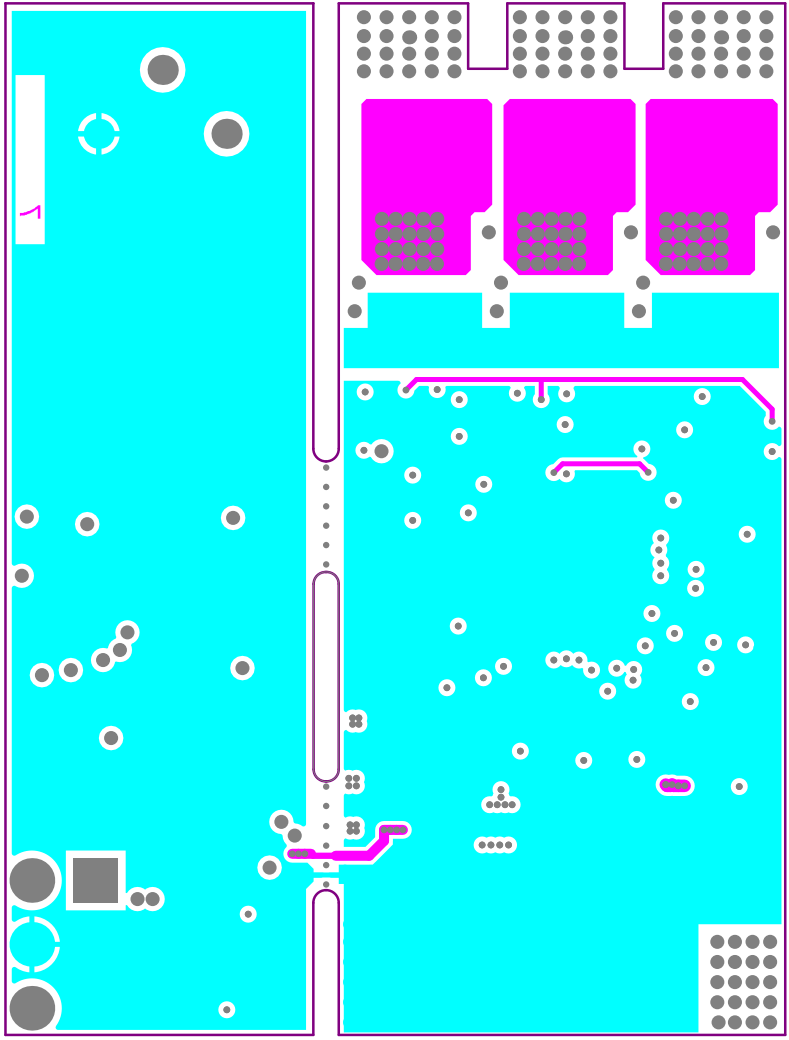
Signal Layer 4

.G4



Signal Layer 5

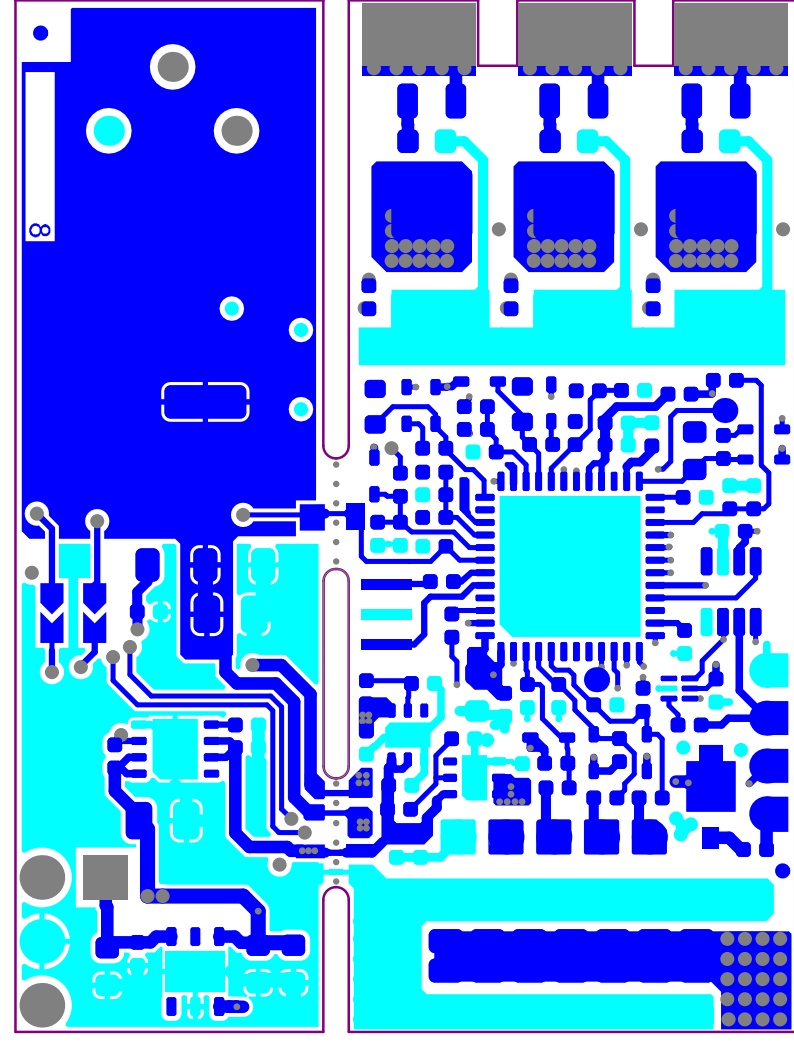
.G5



Signal Layer 6

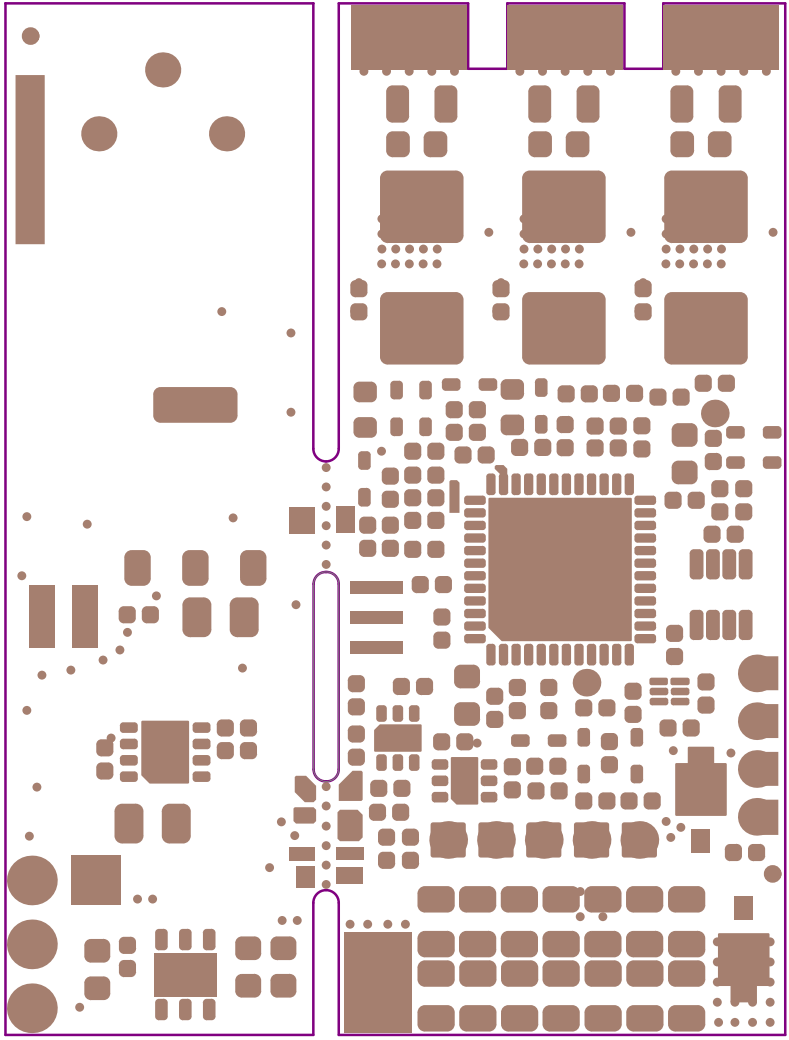
.G6

Bottom Layer



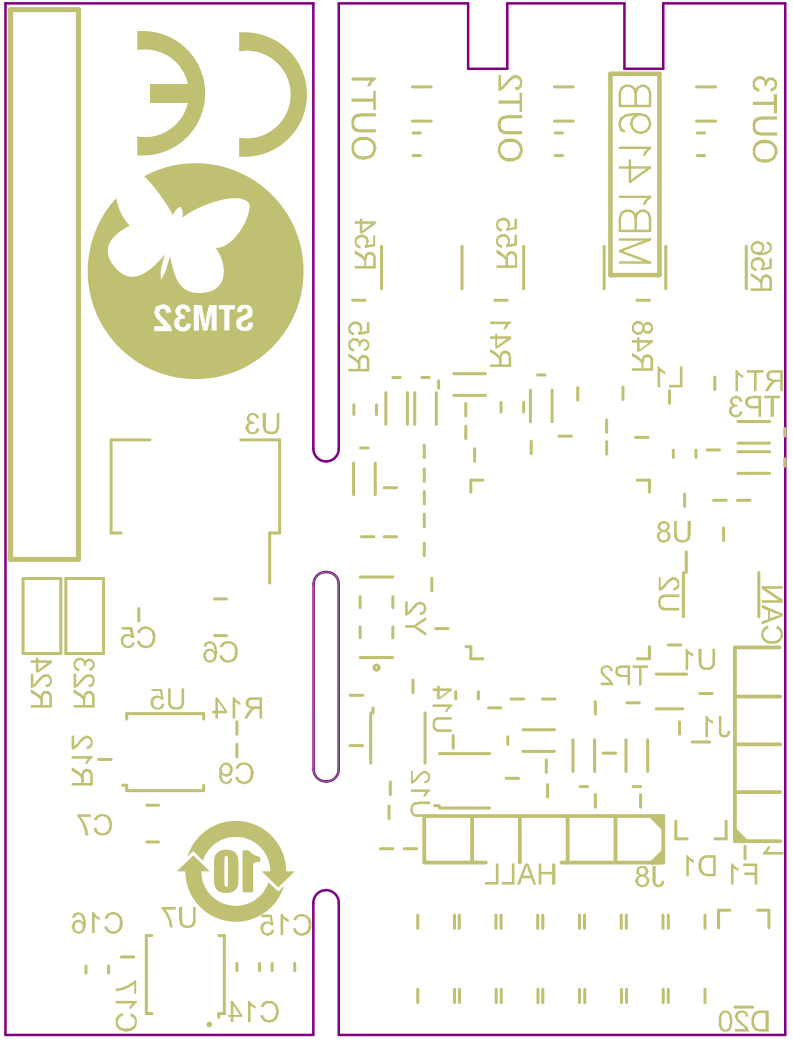
.GBL

Bottom Solder

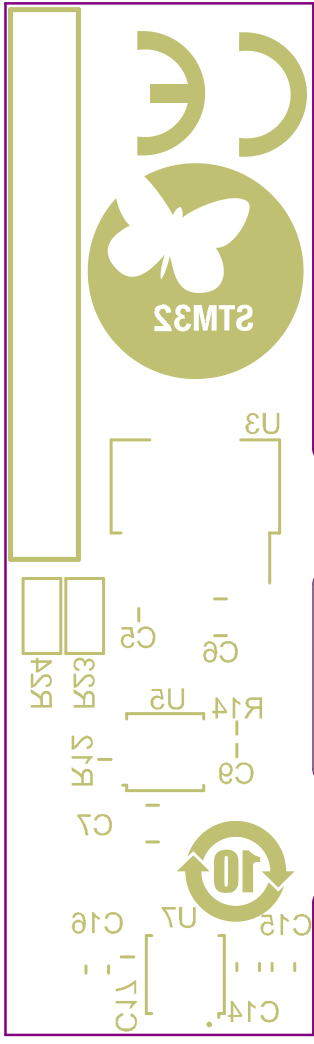


.GB2

Bottom Overlay



BOG



MINIMUM PARAMETERS

DEFAULT

TRACKS : 0.200mm

GAPS : 0.150mm

DRILL SIZE : 0.100mm

PCB : TYPE 4

ASPECT-RATIO, AXE Z :

6:1 to 8:1

LEVEL "B"

PCB SPECIFICATIONS :

A. MATERIAL :

B. MATERIAL FAMILY :

C. SOLDERMASK COLOR :

D. SILKSCREEN COLOR :

E. SURFACE FINISH :

F. IMPEDANCE CONTROL :

G. THROUGH VIA :

H. STACK-UP :

FR-4

N/A

☐ GREEN

☒ WHITE

☒ ENIG

☐ HASL

☒ NO

☐ TG-170

☒ TG-150

☐ TG-140

☒ BLUE

☐ YELLOW

☐ IMMERSION SILVER

☐ HASL (PB-FREE)

☐ YES

☐ RED

☐ BLACK

☐ IMMERSION TIN

☐ GOLDEN FINGER

☐ NO

☐ BLACK

☐ Blue ink PANTONE 2955

☐ IMMERSION SILVER

☐ GOLDEN FINGER

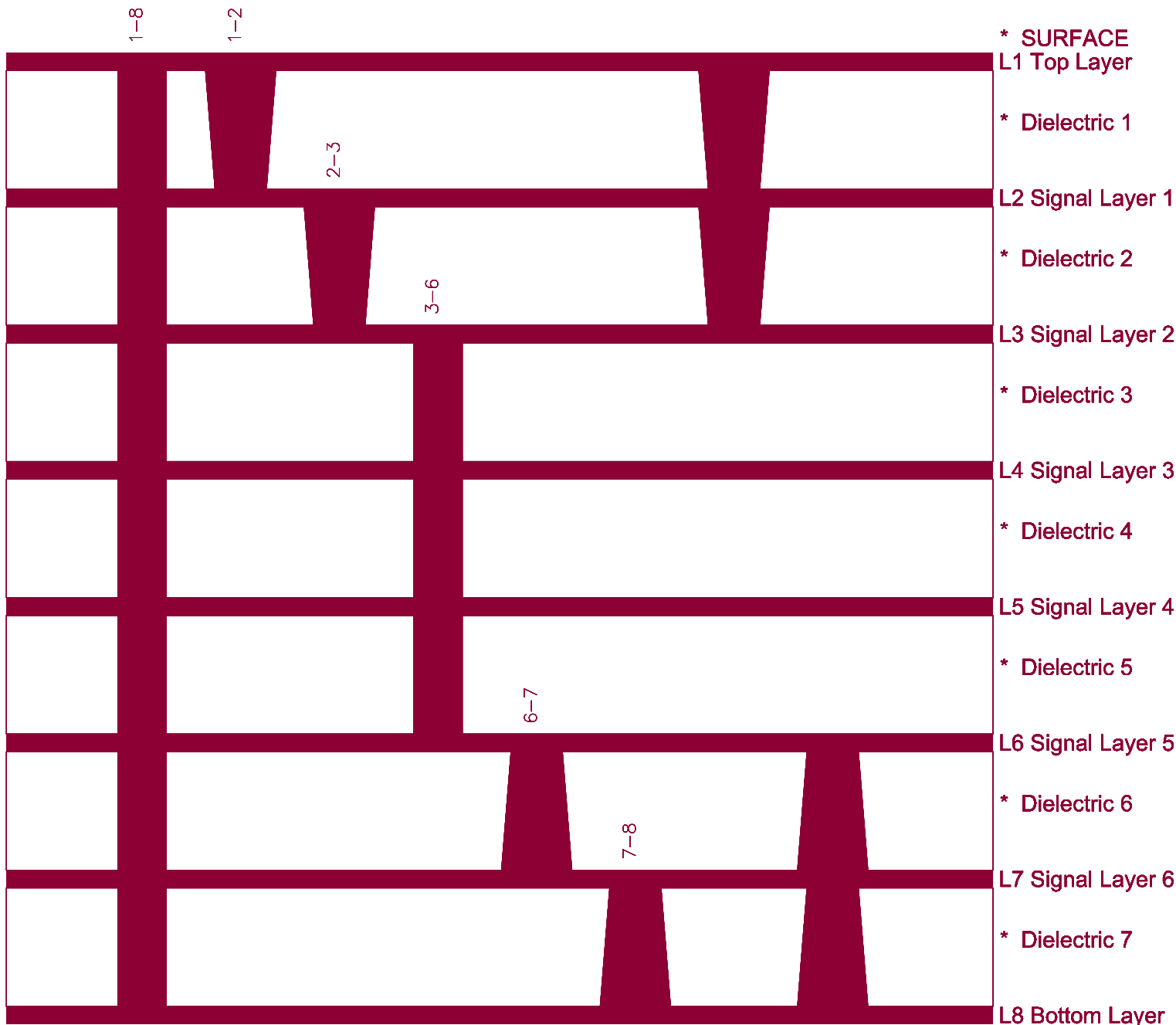
☐ YES

(SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

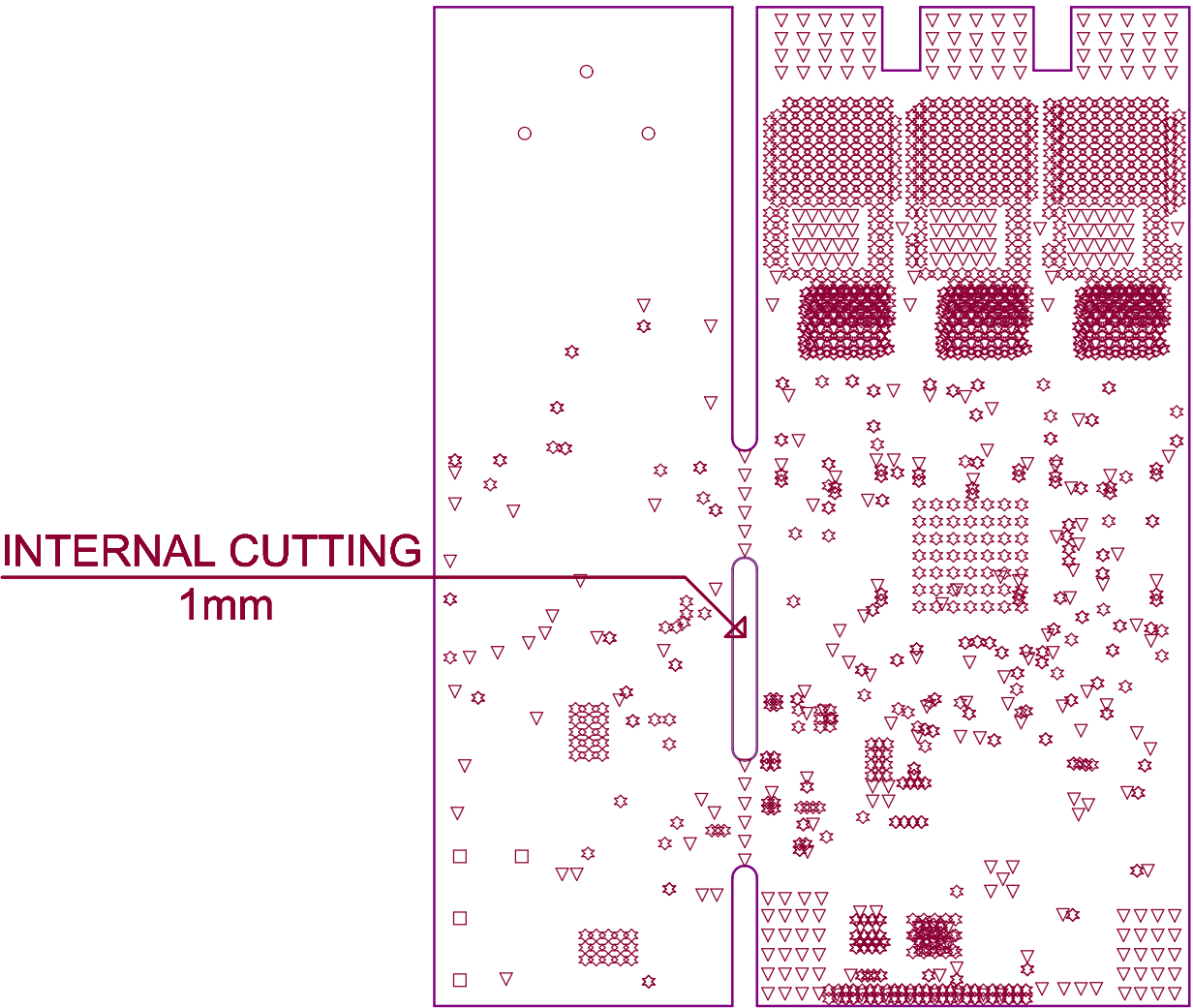
PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



DESIGN CROSS SECTION CHART
TOTAL THICKNESS 1.55633mm



Drill Drawing

.DRL

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	497	0,100mm (3,94mil)	PTH	Round	Signal Layer 1 - Signal Layer 2	Via
	497 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	499	0,100mm (3,94mil)	PTH	Round	Signal Layer 6 - Bottom Layer	Via
	499 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	309	0,100mm (3,94mil)	PTH	Round	Signal Layer 5 - Signal Layer 6	Via
	309 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	484	0,100mm (3,94mil)	PTH	Round	Top Layer - Signal Layer 1	Via
	484 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	155	0,254mm (10,00mil)	PTH	Round	Signal Layer 2 - Signal Layer 5	Via
	155 Total					

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad
	229	0,254mm (10,00mil)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
	3	0,800mm (31,50mil)	PTH	Round	Top Layer - Bottom Layer	Pad
	4	0,991mm (39,00mil)	PTH	Round	Top Layer - Bottom Layer	Pad
	236 Total					

Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0,010mm	3,5	
3	Top Layer	Copper	0,035mm		
4	Dielectric 1		0,074mm	4,5	
5	Signal Layer 1	Copper	0,035mm		
6	Dielectric 2		0,074mm	4,5	
7	Signal Layer 2	Copper	0,035mm		
8	Dielectric 3		0,180mm	4,5	
9	Signal Layer 3	Copper	0,035mm		
10	Dielectric 4		0,600mm	4,5	
11	Signal Layer 4	Copper	0,035mm		
12	Dielectric 5		0,180mm	4,5	
13	Signal Layer 5	Copper	0,035mm		
14	Dielectric 6		0,074mm	4,5	
15	Signal Layer 6	Copper	0,035mm		
16	Dielectric 7		0,074mm	4,5	
17	Bottom Layer	Copper	0,035mm		
18	Bottom Solder	Solder Resist	0,010mm	3,5	
19	Bottom Overlay				